

FNCC

Characteristics

1. Because of excellent resistance to solder temperature, it bears up against flow-soldering process and is used consequently for a wide range of parts of high-class electronic equipment.
2. Excellent flexibility
3. Little resin-flow during pressing

Specifications for Standard Products

Thickness of base film (μm)		25
Adhesive	Classification	Thermosetting Resin
	Thickness (μm)	35
Releasing Materials on Adhesive Surface		Release Paper
Standard Size (μm)		250/500mmxRoll (100m)

Caution

1. Time and temperature gradually promote a change from the semi-cured to the fully cured adhesive state.
2. Keep the coverlay at 5 below 60% RH.

An Example of Processing Method

1. Setting at room temp.
2. Removing Air (about 5 times)
3. Apply pressure (20 to 40 kg/cm^2)
4. Temp. Elevation
5. Removing Air again at 100
6. Apply pressure (20 to 40 kg/cm^2)
7. Removing Air again at 160 to 180
8. Press-bonding at 160 to 180 and higher pressure

of 20 to 40kg/ cm² for 40 to 60 min.

9.Cooling

10.Taking out

Examples of Characteristic Properties of FNCC

Test Item		Unit	Treatment conditions	Properties	Test methods
Insulation resistance(RX)		Ω	C-90/20/65	3.0×10^{12}	JIS-C-6471 { IPC-FC-232B for test patterns }
			+96/40/90	1.0×10^{12}	
Surface resistance (RS)		Ω	C-90/20/65	1.0×10^{15}	JIS-C-6471
			+96/40/90	5.0×10^{14}	
Volume resistance (RS)		Ω -cm	C-90/20/65	5.0×10^{14}	JIS-C-6471
			+96/40/90	1.0×10^{14}	
Peel Strength	Glossy side of Copper foil	Kgf/cm	A	0.9	IPC-FC-232B
			E-1/200	0.8	
	Etched side of polyimide film base		A	1.2	
			E-1/200	1.2	
Solder temp resistance			A	300/30s ec	IPC-FC-232B
Resistance to heat aging			A	No change in appearance E-1/200 treatment	JIS-C-6481

Chemical resistance		A	No change in appearance after immersion separately for 15min at room temp.in following chemicals Toluene, MEK, Methyl alcohol,Trichlor ethylene,10%HC1,10%KCH,10% NaOH	IPC-FC-232B
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